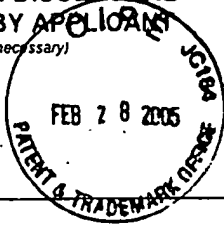


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		Application Number	10/775,890
		Filing Date	February 9, 2004
		First Named Inventor	Sur, Biswajit
		Group Art Unit	2818
		Examiner Name	Huynh, Andy
Sheet 1 of 1		Attorney Docket No: 884.319US2	

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ah	US-4,654,966	04/07/1987	Kohara, Masanobu, et al.	10/03/1985

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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS				
Examiner Initials *	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		T ²

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Application Number	Unknown
Filing Date	Even Date Herewith
First Named Inventor	Sur, Biswajit
Group Art Unit	Unknown
Examiner Name	Unknown

Sheet 1 of 1

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Andrew M. [Signature]

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